

ABSTRACT

SEMICONDUCTOR DIE DE-PROCESSING USING A DIE HOLDER AND CHEMICAL MECHANICAL POLISHING

A method and apparatus for removing layers from a circuit side of a semiconductor die includes the use of a holder, for example a semiconductor wafer having an opening therein for receiving the semiconductor die. Additionally the holder can include one or more layers thereover which are removed at a similar rate as those layers which comprise the semiconductor die. A die is placed into the opening and a circuit side of the die is aligned with a front side of the holder, for example using a generally planar surface, and is secured to the holder with an adhesive material. Using a holder reduces uneven layer removal which is known to occur in conventional processing, for example excessive removal at the edges of the die. A potting jig which aids in aligning and securing the die to the holder is also described.